

Title (en)

Method of cutting a web having at least an adhesive side laying on a protective substrate into individual finished elements

Title (de)

Verfahren zum Stanzen von einer zumindest einseitig klebend ausgerüsteten Bahn, die sich auf einem Abdeckmaterial befindet, in einzelne Stanzlinge

Title (fr)

Procédé de découpe d'une bande ayant au moins un côté adhésif s'appuyant sur une couche de protection en éléments finis individuels

Publication

**EP 1498229 B1 20100331 (DE)**

Application

**EP 04013991 A 20040615**

Priority

DE 10332435 A 20030716

Abstract (en)

[origin: EP1498229A2] A cross punching process defines a single stamping line to divide the material length across its full width, into individual punched parts. The line deviates from the straight, and the covering material of the length is not or only slightly cut. The cross punching is carried out at an angle of mainly 90[deg] to the direction of the material length. The line may be curved, wave-shaped, saw tooth-like and/or zig-zag-shaped. The length consists of a layer of adhesive or a base material with an adhesive coating on one or both sides. The covering material has an anti-adhesive coating on both sides, and the degree of deflection of the anti-adhesive coating is the same as that of the adhesive material.

IPC 8 full level

**B26D 1/00** (2006.01); **B26D 3/08** (2006.01); **B26D 3/10** (2006.01); **B65H 35/06** (2006.01); **B65H 35/07** (2006.01); **C09J 7/02** (2006.01); **C09J 201/00** (2006.01); **B26F 1/40** (2006.01)

CPC (source: EP KR US)

**B26D 1/00** (2013.01 - KR); **B26D 3/085** (2013.01 - EP US); **B26D 3/10** (2013.01 - EP US); **B65H 35/06** (2013.01 - KR); **B26F 1/40** (2013.01 - EP US); **Y10T 156/1052** (2015.01 - EP US); **Y10T 156/1064** (2015.01 - EP US)

Cited by

EP1964621A1

Designated contracting state (EPC)

DE ES FR GB IT

DOCDB simple family (publication)

**EP 1498229 A2 20050119**; **EP 1498229 A3 20050706**; **EP 1498229 B1 20100331**; CN 100351060 C 20071128; CN 1575942 A 20050209; DE 10332435 A1 20050210; DE 502004010955 D1 20100512; ES 2340583 T3 20100607; JP 2005036225 A 20050210; KR 20050009210 A 20050124; US 2005011608 A1 20050120

DOCDB simple family (application)

**EP 04013991 A 20040615**; CN 200410071246 A 20040716; DE 10332435 A 20030716; DE 502004010955 T 20040615; ES 04013991 T 20040615; JP 2004198487 A 20040705; KR 20040055205 A 20040715; US 83017204 A 20040421